Session: TU3E

Packaging and Interconnect Technologies

Chair
J. Pavio
Motorola

Co-Chair
M. Harris
Georgia Tech. Research Inst.

Packaging and interconnect technologies play a vital role in today's telecommunications systems. It is the enabling technology for microwave performance, device cost/affordability and manufacturability. This session will show advancements in performance and affordability with emphasis on plastic packages, flip chips, and vertical interconnects.

1:40 pm - 3:30 pm Tuesday, June 18, 1996
Room 130